TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN#20251006000.1
Qualification of FFAB as an additional Fab site option, Die Revision, Datasheet and TIEM as an additional Assembly site option for select devices
Change Notification / Sample Request

Date: October 06, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251006000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LP324PWR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251006000.1	**PCN Date:**	October 06, 2025
Title:	Qualification of FFAB as an additional Fab site option, Die Revision, Datasheet, and TIEM as an additional Assembly site option for select devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	January 04, 2026	**Sample requests accepted until:**	December 05, 2025*

*Sample requests received after December 05, 2025 will not be supported.

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
SFAB	JI1	150mm	FFAB	SLM	200mm

The die was also changed as a result of the process change.

Construction differences are as follows:

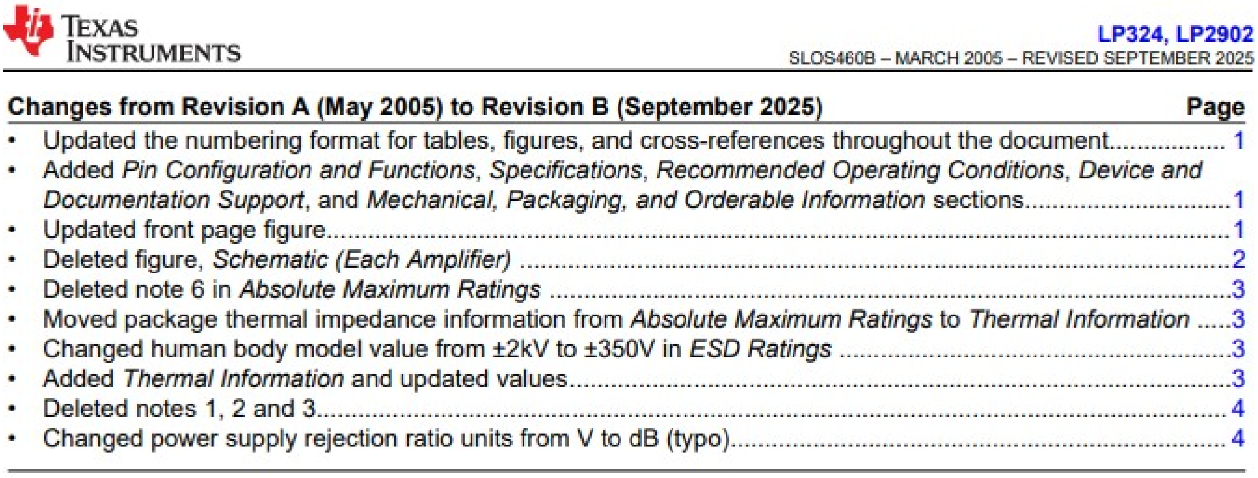
Group 1 device (D)

	Current site	Additional site
Assembly site	**FMX**	**TIEM**
Mount compound	4147858	8075531
Mold compound	4211880	8096859
Lead finish	NiPdAu	Matte Sn

Group 2 device (PW)

	Current site	Additional site
Assembly site	**MLA**	**TIEM**
Wire diam/type	0.96mil Cu	0.8mil Cu
Mount compound	4147858	4211470
Mold compound	4211471	4228573
Lead finish	NiPdAu	Matte Sn
Marking differences	LP324: TI Letter LP2902: TI logo, with G4	LP324: TI Letter, Mold cavity ID LP2902: TI Letter, Remove G4, Mold cavity ID

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



TEXAS INSTRUMENTS

LP324, LP2902

SLOS460B – MARCH 2005 – REVISED SEPTEMBER 2025

Changes from Revision A (May 2005) to Revision B (September 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document................ 1
- Added *Pin Configuration and Functions*, *Specifications*, *Recommended Operating Conditions*, *Device and Documentation Support*, and *Mechanical, Packaging, and Orderable Information* sections.............................1
- Updated front page figure...1
- Deleted figure, *Schematic (Each Amplifier)* 2
- Deleted note 6 in *Absolute Maximum Ratings* 3
- Moved package thermal impedance information from *Absolute Maximum Ratings* to *Thermal Information* 3
- Changed human body model value from ±2kV to ±350V in *ESD Ratings* 3
- Added *Thermal Information* and updated values...3
- Deleted notes 1, 2 and 3...4
- Changed power supply rejection ratio units from V to dB (typo)...4

The datasheet number will be changing.

Device Family	Change From:	Change To:
LP324, LP2902	SLOS460A	**SLOS460B**

Qual details are provided in the Qual Data Section.
Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SFAB	SHE	USA	Sherman
FFAB	**TID**	**DEU**	**Freising**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
B	**C**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI Malaysia	MLA	MYS	Kuala Lumpur
TI Mexico	MEX	MEX	Aguascalientes
TI Melaka	**GNZ**	**MYS**	**Melaka**

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) ~~0033317~~
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Group 1 Product Affected:

LP2902DR	LP324DR

Group 2 Product Affected:

LP2902PWR	LP324PWR

Group 1
Qualification Report

Approve Date 16-SEPTEMBER-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LP2902DR	Qual Device: LP324DR	QBS Package Reference: DS36C200M/NOPB	QBS Package Reference: DS91C180TMAX/NOPB	QBS Package Reference: LM6172IM	QBS Package Reference: LM6172IM	QBS Process Reference: LM2576HVT-5.0/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	1/77/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	3/231/0	1/77/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	1/77/0	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	1/800/0	3/2400/0

SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/22/0	-	1/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	-	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	3/9/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	3/9/0	1/3/0	-
ESD	E2	ESD HBM	-	350 Volts	-	1/3/0	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	-	-	3/9/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	1/30/0	1/30/0	3/90/0	1/30/0	3/90/0
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	-	-	-	-	-

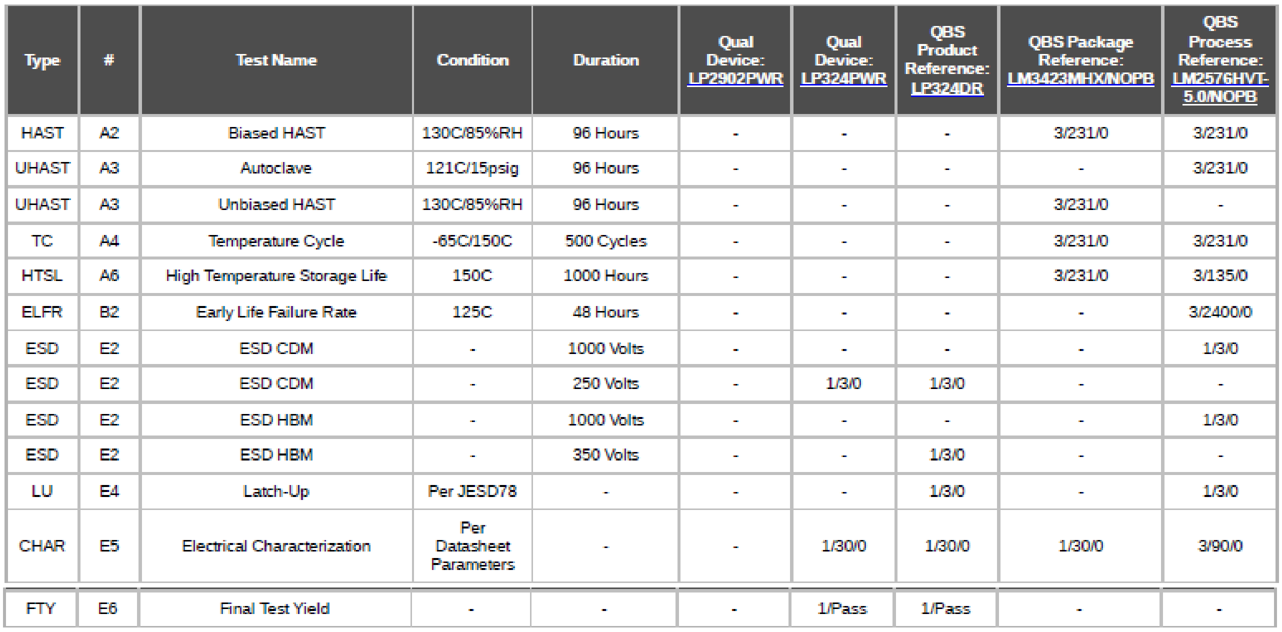
QBS: Qual By Similarity, also known as Generic Data
Qual Device LP2902DR is qualified at MSL1 260C
Qual Device LP324DR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2503-079

Group 2
Qualification Report

Approve Date 18-September-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed



Type	#	Test Name	Condition	Duration	Qual Device: LP2902PWR	Qual Device: LP324PWR	QBS Product Reference: LP324DR	QBS Package Reference: LM3423MHX/NOPB	QBS Process Reference: LM2576HVT-5.0/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	3/135/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	350 Volts	-	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	1/30/0	1/30/0	3/90/0
FTY	E6	Final Test Yield	-	-	-	1/Pass	1/Pass	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device LP2902PWR is qualified at MSL1 260C
Qual Device LP324PWR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2503-078

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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